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APPLICATION 1	NO. F	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/765,094 01/28/2004		Tatsuya Usami	8022-1067	9832	
466	7590	03/24/2005		EXAMINER	
YOUNG	3 & THOMI	PSON	WILSON, SCOTT R		
745 SOU	TH 23RD ST	ΓREET			
2ND FLOOR				ART UNIT	PAPER NUMBER
ARLING	ARLINGTON, VA 22202			2826	
				DATE MAILED: 03/24/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/765,094	USAMI, TATSUYA				
Office Action Summary	Examiner	Art Unit				
	Scott R. Wilson	2826				
The MAILING DATE of this communication a	appears on the cover sheet with the o	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REF THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a r - If NO period for reply is specified above, the maximum statutory perions - Failure to reply within the set or extended period for reply will, by start Any reply received by the Office later than three months after the may earned patent term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no event, however, may a reply be tirreply within the statutory minimum of thirty (30) day od will apply and will expire SIX (6) MONTHS from tute, cause the application to become ABANDONE	mely filed /s will be considered timely. I the mailing date of this communication. ED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 28	3 January 2004.					
	his action is non-final.					
.—	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ☐ Claim(s) 1-16 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-3 and 6-16 is/are rejected. 7) ☐ Claim(s) 4 and 5 is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or election requirement.						
Application Papers						
9) The specification is objected to by the Examination 10) The drawing(s) filed on 28 January 2004 is/a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. The oath or declaration is objected to by the	re: a)⊠ accepted or b)☐ objected he drawing(s) be held in abeyance. Se rection is required if the drawing(s) is ob	e 37 CFR 1.85(a). ojected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for forei a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the priority docume application from the International Bure * See the attached detailed Office action for a li	ents have been received. ents have been received in Applicat riority documents have been receive eau (PCT Rule 17.2(a)).	ion No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892)	4) Interview Summary					
 Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date 1/28/04. 	Paper No(s)/Mail D 5) Notice of Informal F 6) Other:	ate Patent Application (PTO-152)				

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 15 and 16 are rejected under 35 U.S.C. 102(b) as being anticipated by Oda. As to claim 15, Oda, Figure 2G, discloses a semiconductor device comprising: a first insulating layer (11) formed on a substrate (9); a trench (5) formed in said first insulating layer; a conductive layer (14) formed in said trench; and a second insulating layer (4a) and (4b) formed between said first insulating layer (11) and said conductive layer (14), wherein said trench has a part which is wider than the other part, a thickness of said second insulating layer adjacent to said wider part is thicker than the other part. Layers (4a) and (4b) are both formed from the same material (paragraph 0111), and may therefore be considered to form a single layer.

As to claim 16, Oda, Figure 2G, discloses that the trench (5) has a width which is wider at an upper part than a lower part, and a thickness of said second insulating layer (4a) and (4b) adjacent to said upper part is thicker than a thickness of said second insulating layer adjacent to said lower part.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Application/Control Number: 10/765,094

Art Unit: 2826

Claims 1-3 and 6-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Oda in view of Takase et al.. As to claim 1, Oda, Figure 2G, discloses a semiconductor device comprising: an insulating layer (11) which is formed on a semiconductor substrate (9); a conducting portion (14)(paragraph 0107) which is formed in said insulating layer; and a modified layer (4a) and (4b) which is formed between said insulating layer and said conducting portion. Layers (4a) and (4b) are both formed from the same material (paragraph 0111), and may therefore be considered to form a single layer. Oda does not disclose expressly that the insulating layer includes hydrogenated polysiloxane. Takase et al., Figure 2A, discloses an insulating film (5) formed in a multilayer interconnect structure, comprising an organosiloxane (col. 5, lines 16-18). Organosiloxane is within the scope of being a hydrogenated polysiloxane (see Andrews, p. 2, Summary, "The types of organic modification vary and range from acrylated urethanes, hydrogenated epoxies and modified acrylics...."). At the time of invention, it would have been obvious to a person of ordinary skill in the art to form the insulating layer (11) of Oda with a hydrogenated polysiloxane. The motivation for doing so would have been form an interlayer dielectric with low dielectric constant (Takase et al., col. 1, lines 20-23). Therefore, it would have been obvious to combine Takase et al. with Oda et al. to obtain the invention as specified in claim 1.

As to claim 2, Oda, Figure 2G, discloses that a portion of the modified layer (4a) and (4b) far from said semiconductor substrate (9) is thicker that a portion of said modified layer near said substrate.

As to claim 3, Oda, Figure 2G, discloses that a portion of the conducting region (14) far from the semiconductor substrate is thicker than a portion nearer the semiconductor substrate.

As to claim 6, Oda, Figure 2G, discloses that the conducting portion is a wiring (paragraph 0002), and said modified layer (4a) and (4b) is formed to attach to a side of said wiring.

As to claim 7, Oda, Figure 2G, discloses that a portion of said conducting portion (14) far from said semiconductor substrate is thicker than a portion of said conducting portion near said semiconductor substrate.

As to claim 8, Oda, Figure 2G, discloses that said conducting portion includes a first conducting portion (13) which is the bottom and side part of said conducting portion, and a second conducting portion (14) which is the remaining part of said conducting portion, both made from copper (paragraph 0107).

Application/Control Number: 10/765,094 Page 4

Art Unit: 2826

As to claims 9-14, the device of Oda in view of Takase et al. would necessarily have to be formed

in order to function, so that the method comprising the means of forming the device is inherent in the

device structure itself.

Allowable Subject Matter

Claim 4 is objected to as being dependent upon a rejected base claim, but would be allowable if

rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The hydrogenated polysiloxane layer of Takase et al. corresponds to the insulating layer (11) of Oda, not

the insulating layer (4a) and (4b) of Oda.

Claim 5 is objected to as being dependent upon a rejected base claim, but would be allowable if

rewritten in independent form including all of the limitations of the base claim and any intervening claims.

No prior art discloses a ladder or porous ladder type hydrogenated polysiloxane.

Any inquiry concerning this communication or earlier communications from the examiner should

be directed to Scott R. Wilson whose telephone number is 571-272-1925. The examiner can normally be

reached on M-F 8:30 - 4:30 Eastern.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor,

Nathan Flynn can be reached on 571-272-1915. The fax phone number for the organization where this

application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application

Information Retrieval (PAIR) system. Status information for published applications may be obtained from

either Private PAIR or Public PAIR. Status information for unpublished applications is available through

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at 866-217-9197 (toll-free).

srw

March 18, 2005

NATHAN J. FLYNN
SUPERVISORY PATENT EXAMINER
TECHNOLOGY PENTER 2800